100% Material Declaration Data Sheet for FFG672

PK091 (v1.5) May 13, 2016

Average Weight : 6.5119 g

Component	Substance Description	CAS # or Description	% of Component	Use in product	Component Weight	Component % of total
Silicon Die					**0.458097**	**7.035%**
	Si	7440-21-3	100.000	basis	0.458097	
Solder Bump					**0.024729**	**0.380%**
	Sn	7440-31-5	63.000	basis	0.015580	
	Pb	7439-92-1	37.000	basis	0.009150	
Solder Paste					**0.048000**	**0.737%**
	Sn	7440-31-5	96.500	metal	0.046320	
	Ag	7440-22-4	3.000	metal	0.001440	
	Cu	7440-50-8	0.500	metal	0.000240	
Capacitor 1					**0.016000**	**0.246%**
	Barium titanium trioxide	12047-27-7	51.100	Ceramic	0.008176	
	Copper	7440-50-8	16.900	Inner electrode	0.002704	
	Nickel	7440-02-0	27.000	Out electrode	0.004320	
	Nickel	7440-02-0	2.000	Plating1	0.000320	
	Tin	7440-31-5	3.000	Plating2	0.000480	
Underfill					**0.056000**	**0.860%**
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.000	basis	0.011200	
	Phenolic resin	trade secret	15.000	basis	0.008400	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.000	basis	0.002800	
	Amine type accelerator	trade secret	5.000	basis	0.002800	
	Silicon dioxide	60676-86-0	51.500	basis	0.028840	
	Carbon black	1333-86-4	1.000	basis	0.000560	
	Additives	trade secret	2.500	Additive	0.001400	
Lid					**3.040000**	**46.684%**
	Cu	7440-50-8	99.450	Main material	3.023280	
	Ni	8049-31-8	0.550	Main material	0.016720	
Lid Adhesive					**0.106000**	**1.628%**
	Aluminum oxide(Al2O3)	1344-28-1	70.000	Main material	0.074200	
	Zinc oxide (ZnO)	1314-13-2	15.000	Main material	0.015900	
	Silicone	Trade Secret	15.000	Main material	0.015900	
Solder Ball					**0.562885**	**8.644%**
	Sn	7440-31-5	95.500	Main material	0.537555	
	Ag	7440-22-4	4.000	Main material	0.022515	
	Cu	7440-50-8	0.500	Main material	0.002814	
Substrate					**2.200189**	**33.787%**
	Copper	7440-50-8	52.18	Main material	1.148059	
	Tin	7440-31-5	0.91	Main material	0.020022	
	Lead	7439-92-1	0.21	Main material	0.004620	
	Silver	7440-22-4	0.02	Main material	0.000440	
	Core	N/A	28.49	Main material	0.626834	
	ABF	N/A	15.26	Main material	0.335749	
	Solder Mask	N/A	2.93	Main material	0.064466	

Revision History

Date	Version	Description of Revisions
03/14/2006	1.0	Initial Initial release.
08/11/2006	1.1	100% Material Declaration.
09/27/2006	1.2	Updated component descriptions.
07/20/2010	1.3	Updated Heat Spreader substance description
04/08/2011	1.4	Updated component descriptions and weights
05/13/2016	1.5	Updated substrate

Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers (“Contractors”). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.

© Copyright 2016 Xilinx